DMG50401

Silicon NPN epitaxial planar type (Tr1) Silicon PNP epitaxial planar type (Tr2)

For general amplification
DMG20401 in SMini6 type package

■ Features

- High forward current transfer ratio h_{FE} with excellent linearity
- ullet Low collector-emitter saturation voltage $V_{\text{CE(sat)}}$
- Halogen-free / RoHS compliant
 (EU RoHS / UL-94 V-0 / MSL: Level 1 compliant)

■ Marking Symbol: A9

■ Basic Part Number

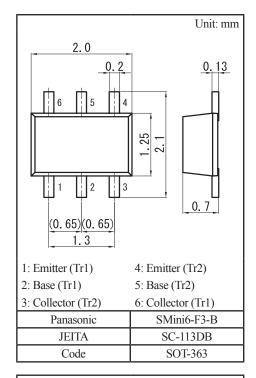
DSC2001 + DSA2001 (Individual)

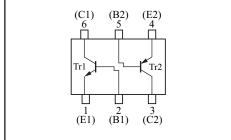
Packaging

DMG504010R Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter		Symbol	Rating	Unit	
Tr1	Collector-base voltage (Emitter open)	V _{CBO}	60	V	
	Collector-emitter voltage (Base open)	V _{CEO}	50	V	
	Emitter-base voltage (Collector open)	V_{EBO}	7	V	
	Collector current	I_{C}	100	mA	
	Peak collector current	I _{CP}	200	mA	
Tr2	Collector-base voltage (Emitter open)	V _{CBO}	-60	V	
	Collector-emitter voltage (Base open)	V _{CEO}	-50	V	
	Emitter-base voltage (Collector open)	V _{EBO}	-7	V	
	Collector current	I_{C}	-100	mA	
	Peak collector current	I _{CP}	-200	mA	
Overall	Total power dissipation	P _T	150	mW	
	Junction temperature	T _j	150	°C	
	Operating ambient temperature	T _{opr}	-40 to +85	°C	
	Storage temperature	T _{stg}	-55 to +150	°C	





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■ Electrical Characteristics $T_a = 25$ °C±3°C

• Tr1

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V_{CBO}	$I_C = 10 \mu A, I_E = 0$	60			V
Collector-emitter voltage (Base open)	V _{CEO}	$I_{\rm C} = 2 \text{ mA}, I_{\rm B} = 0$	50			V
Emitter-base voltage (Collector open)	V_{EBO}	$I_E = 10 \mu A, I_C = 0$	7			V
Collector-base cutoff current (Emitter open)	I _{CBO}	$V_{\rm CB} = 20 \text{ V}, I_{\rm E} = 0$			0.1	μΑ
Collector-emitter cutoff current (Base open)	I _{CEO}	$V_{CE} = 10 \text{ V}, I_{B} = 0$			100	μА
Forward current transfer ratio	h _{FE}	$V_{CE} = 10 \text{ V}, I_{C} = 2 \text{ mA}$	210		460	_
Collector-emitter saturation voltage	V _{CE(sat)}	$I_C = 100 \text{ mA}, I_B = 10 \text{ mA}$		0.13	0.3	V
Transition frequency	f_T	$V_{CE} = 10 \text{ V}, I_{C} = 2 \text{ mA}$		150		MHz
Collector output capacitance (Common base, input open circuited)	C _{ob}	$V_{CB} = 10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		1.5		pF

 $Note)\ Measuring\ methods\ are\ based\ on\ JAPANESE\ INDUSTRIAL\ STANDARD\ JIS\ C\ 7030\ measuring\ methods\ for\ transistors.$

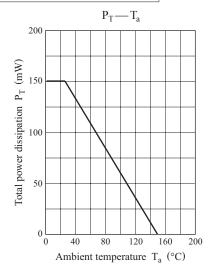
• Tr2

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V_{CBO}	$I_{\rm C} = -10 \mu \text{A}, I_{\rm E} = 0$	-60			V
Collector-emitter voltage (Base open)	V _{CEO}	$I_{\rm C} = -2 \text{ mA}, I_{\rm B} = 0$	-50			V
Emitter-base voltage (Collector open)	V_{EBO}	$I_E = -10 \mu A, I_C = 0$	-7			V
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{\rm CB} = -20 \text{ V}, I_{\rm E} = 0$			-0.1	μΑ
Collector-emitter cutoff current (Base open)	I _{CEO}	$V_{CE} = -10 \text{ V}, I_{B} = 0$			-100	μΑ
Forward current transfer ratio	h _{FE}	$V_{CE} = -10 \text{ V}, I_{C} = -2 \text{ mA}$	210		460	_
Collector-emitter saturation voltage	V _{CE(sat)}	$I_C = -100 \text{ mA}, I_B = -10 \text{ mA}$		-0.2	-0.5	V
Transition frequency	f_T	$V_{CE} = -10 \text{ V}, I_{C} = -2 \text{ mA}$		150		MHz
Collector output capacitance (Common base, input open circuited)	C _{ob}	$V_{CB} = -10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		2		pF

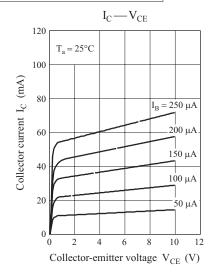
Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

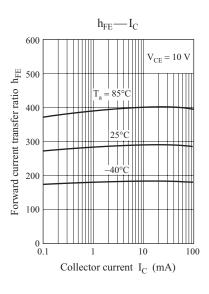
Ver. EED 2

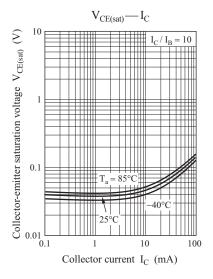
Common characteristics chart

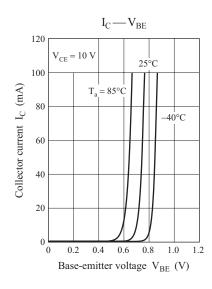


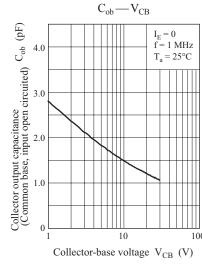
Characteristics charts of Tr1

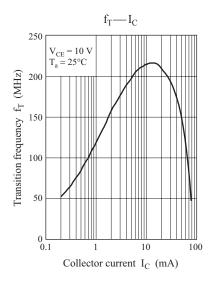




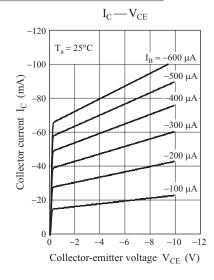


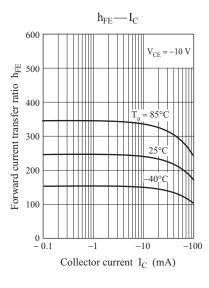


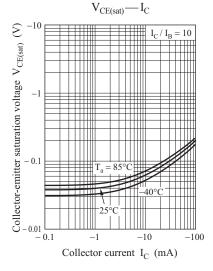


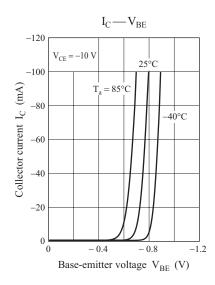


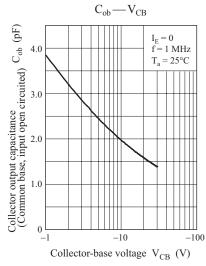
Characteristics charts of Tr2

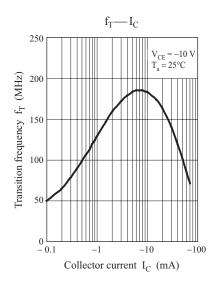






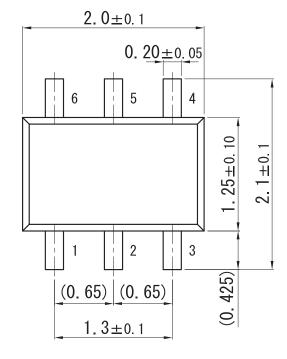


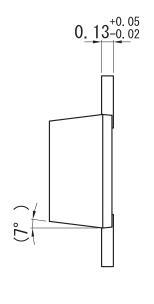


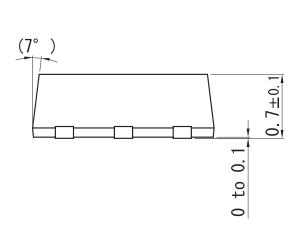


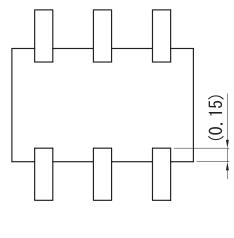
SMini6-F3-B

Unit: mm

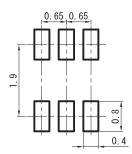








■ Land Pattern (Reference) (Unit: mm)



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